



2827

AMENDMENT TRANSMITTAL LETTER			Docket No. TESSERA 3.0-132 DIV
Application No. 09/650,834	Filing Date August 30, 2000	Examiner David E. Graybill	Art Unit 2827

Applicant(s): Joseph Link

Invention: SPACER PLATE SOLDER BALL PLACEMENT FIXTURE AND METHODS THEREFOR

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	17	- 20 =		x	0.00
Independent Claims	3	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify): Extension for response within third month					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					

- ☒ Large Entity ☐ Small Entity
- ☒ No additional fee is required for this amendment.
- ☐ Please charge Deposit Account No. 12-1095 in the amount of \$.
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of \$ to cover the filing fee is enclosed.
- ☐ Payment by credit card. Form PTO-2038 is attached.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 12-1095
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- ☒ Credit any overpayment.
- ☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

Michael J. Doherty
Michael J. Doherty
Attorney Reg. No.: 40,592

Dated: March 11, 2003

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: March 11, 2003

Signature: Michael J. Doherty (Michael J. Doherty)

(Michael J. Doherty)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

For: SPACER PLATE SOLDER BALL
PLACEMENT FIXTURE AND METHODS
THEREFOR

AMENDMENT

Dear Sir:

In response to the Office Action dated September 12, 2002, please amend the above-identified U.S. patent application as follows:

IN THE ABSTRACT:

A stencil assembly for placing conductive elements over conductive pads accessible at a first surface of a microelectronic element includes a main body having a top surface and a bottom surface and a plurality of openings extending between the top and bottom surfaces, the main body being adapted for overlying the first surface of the microelectronic element so that the openings are in substantial alignment with the pads of the microelectronic element. The stencil assembly also includes a spacer element under the bottom

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